STSF-191M50A
Saw Filter
Preliminary Specifications

Item		Minimum	Typical	Maximum	Unit
Center Frequency	-		191.00		MHz
Insertion Loss	189.60-192.40MHz	-	1.5	5.0	dB
Ripple Deviation	189.60-192.40MHz	-	0.3	1.0	dB
VSWR	189.60-192.40MHz		1.8	2.5	
1dBBandwidth	BW1dB	2.8	3.6	-	MHz
40dBBandwidth	BW40dB	-	6.7	8.0	MHz
Attenuation	DC-185.50MHz	-	48.0	-	dB
	197.50-1000.00MHz	-	44.0	-	dB
NOTE	TestTemperature:25°C±2				

Maximum Ratings

Item		Value	Unit
OperationTemperature	T	-10~ +50	℃
StorageTemperature	T_{stg}	-40~ +85	℃
RFPowerDissipation	P	10	dBm

Figure1 ElectricalCharacteristics:Frequencyresponse.(narrowband)

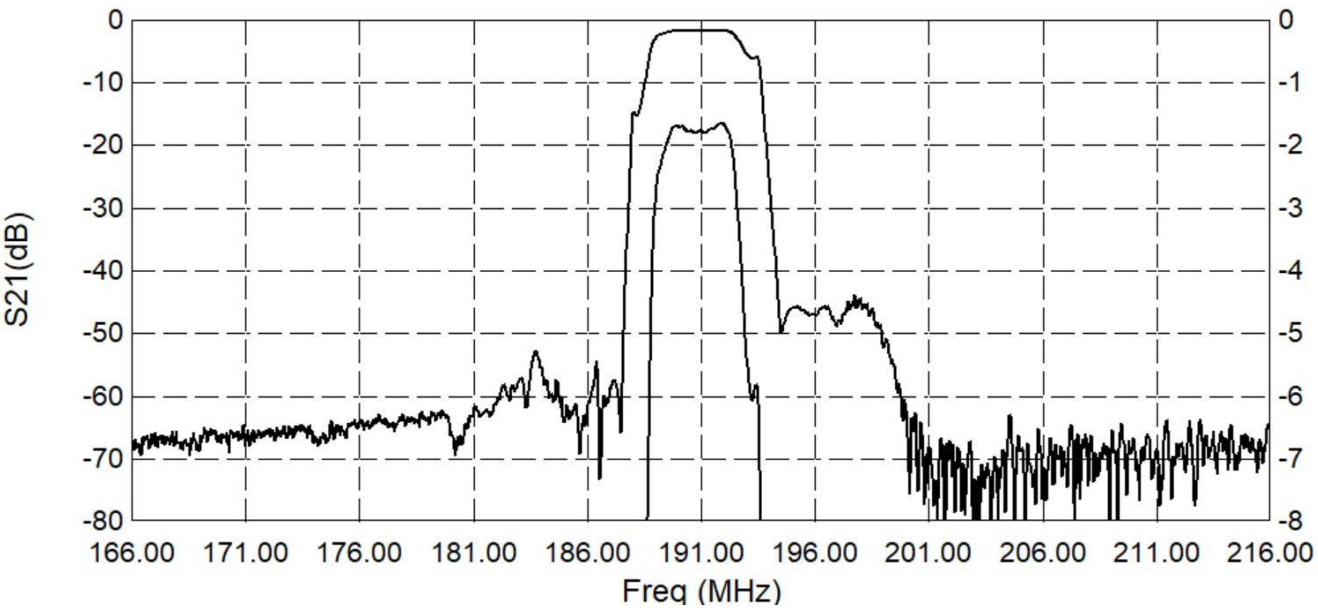
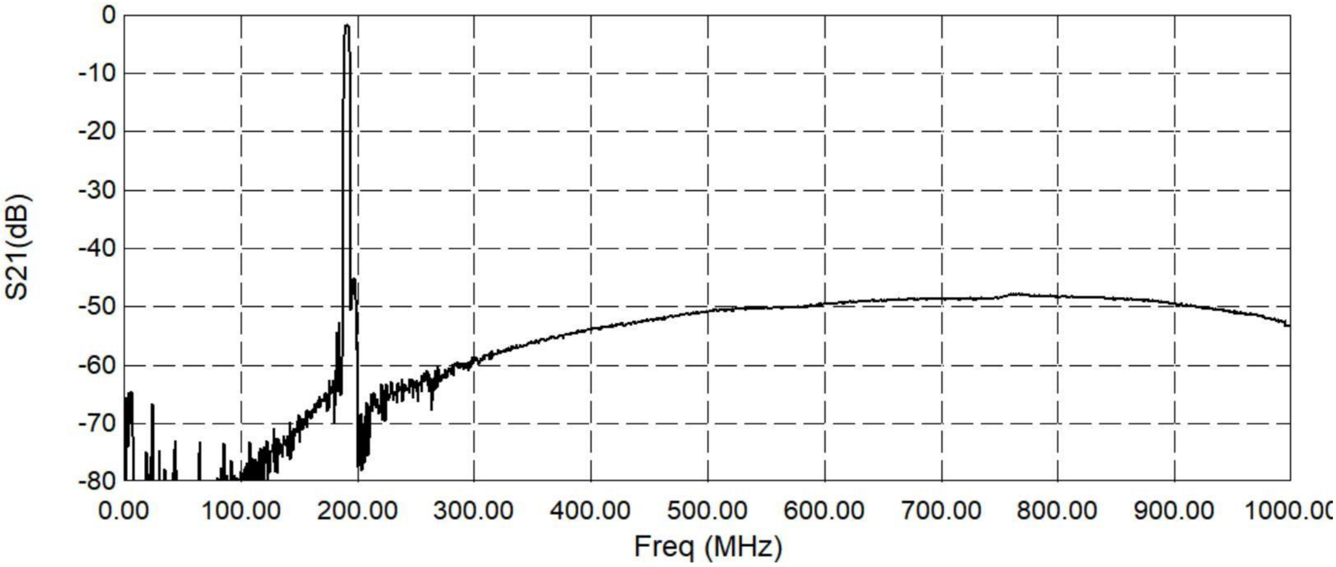
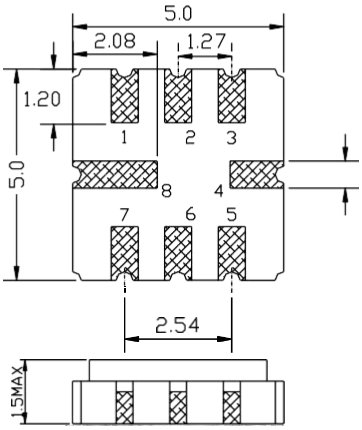


Figure2 ElectricalCharacteristics:Frequencyresponse.(wideband)

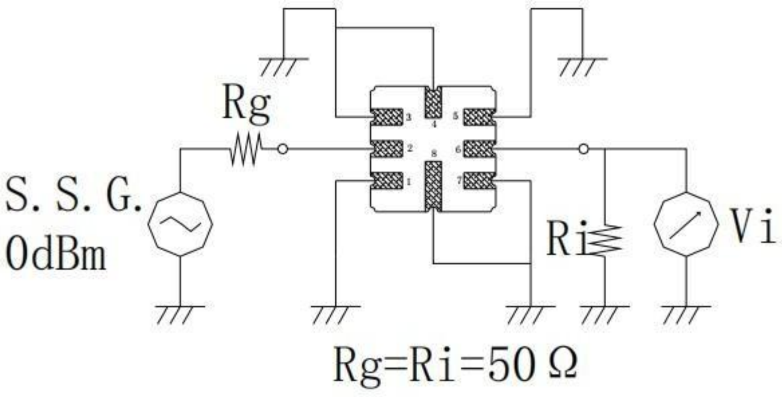


Package & Dimensions

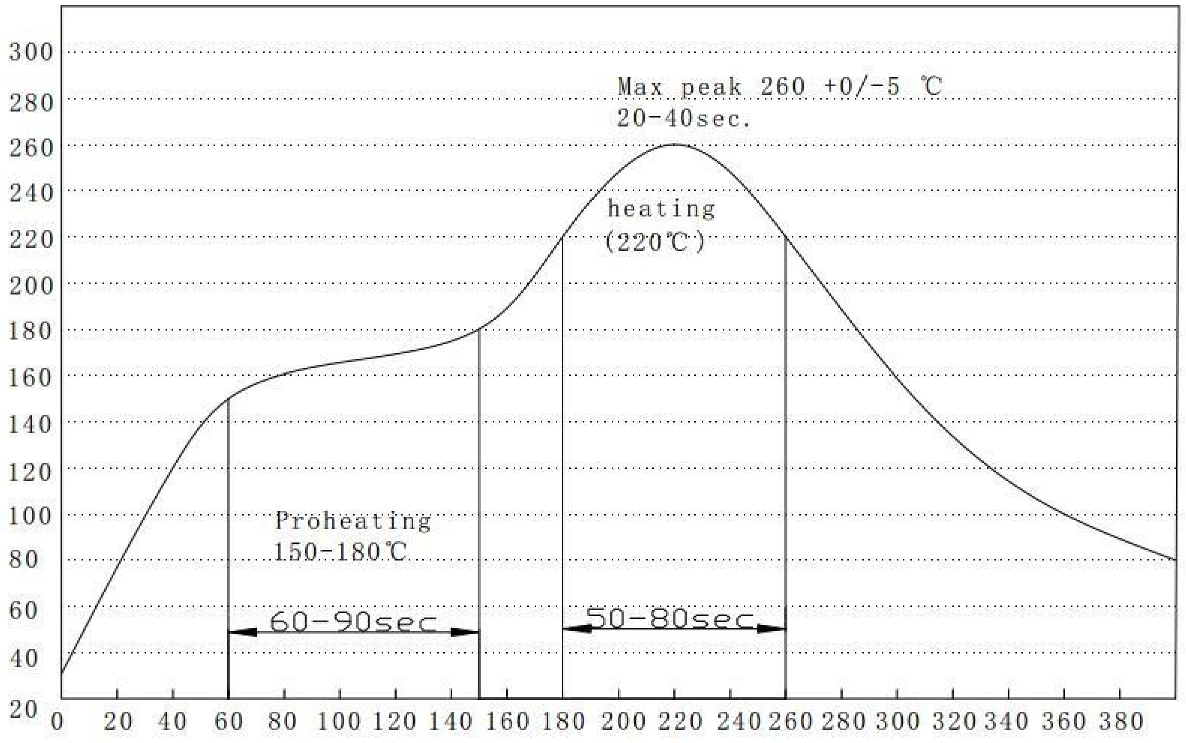


PinNo.	Description
2	Input
6	Output
1,3,4,5,7,8	Ground

Test circuit



Recommended SMT Solder Profile



Reliability

No.	Test item	Test condition
1	Temperature Storage	Temperature: 85℃±2℃ , Duration: 250h , Recovery time: 2h±0.5h (2) Temperature: –55℃±3℃ , Duration: 250h ,Recovery time: 2h±0.5h

2	Humidity Test	Conditions: 60℃±2℃ ,90~95%RH Duration:250h
3	Thermal Shock	Heat cycle conditions: TA=-55℃±3℃, TB=85℃±2℃, t1=t2=30min, Switch time: ≤3min, Cycle time: 100 times, Recovery time: 2h±0.5h.
4	Vibration Fatigue	Frequency of vibration:10~55Hz Amplitude:1.5mm Directions: X,Y and Z Duration: 2h
5	Drop Test	Cycle time:10times Height:1.0m
6	Solder Ability Test	Temperature:245℃±5℃ Duration:3.0s--5.0s Depth: DIP--2/3 ,SMD--1/5
7	Resistance to Soldering Heat	(1) Thickness of PCB:1mm , Solder condition: 260℃±5℃ , Duration:10±1s (2) Temperature of Soldering Iron: 350℃±10℃, Duration: 3~4s, Recovery time : 2 ± 0.5h